

FORM PTO-1449 (SUBSTITUTE) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))				Attorney Docket No.: MAS-FIN-403 Appl. No.: <u>10/1651, 856</u> Applicant: BERND GOLLER ET AL. Filing Date: August 29, 2003 Group Art Unit:			
EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
<u>mr</u>	A	5,306,670	4/26/94	Mowatt et al.			
<u> </u>	B	5,923,958	7/13/99	Chou			
<u> </u>	C	5,990,546	11/23/99	Igarashi et al.			
<u> </u>	D	5,032,543	7/16/91	Black et al.			
<u> </u>	E	5,879,964	3/9/99	Paik et al.			
<u> </u>	F	5,972,735	10/26/99	Dominic			
<u> </u>	G	5,144,747	9/8/92	Eichelberger			
<u> </u>	H	6,239,482 B1	5/29/01	Fillion et al.			
<u> </u>	I	2003/0040142 A1	2/27/03	Lin et al.			
FOREIGN PATENT DOCUMENT							
		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES NO
<u>mr</u>	J	44 27 309 A1	2/15/96	Germany			
<u> </u>	K	2001093940 A	4/6/01	Japan			
<u> </u>	L	0 611 129 B1	8/17/94	Europe			
<u> </u>	M	88/03704	5/19/88	WIPO			
<u> </u>	N	97/22993	6/26/97	WIPO			
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>
EXAMINER <u>flawrke</u>				DATE CONSIDERED <u>Aug 8, 2004</u>			

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<i>hrv</i>	J	92/17901	10/15/92	WIPO			
<i>hrv</i>	K	96/04611	2/15/96	WIPO			
<i>L</i>	M						
	N						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>hrv</i>	Okuno, A. et al.: "High Reliability, High Density, Low Cost Packaging Systems for Matrix Systems for Matrix BGA and CSP by Vacuum Printing Encapsulation Systems (VPES)", IEEE Transactions on Advanced Packaging, Vol. 22, No. 3, August 1999, pp. 391-397
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